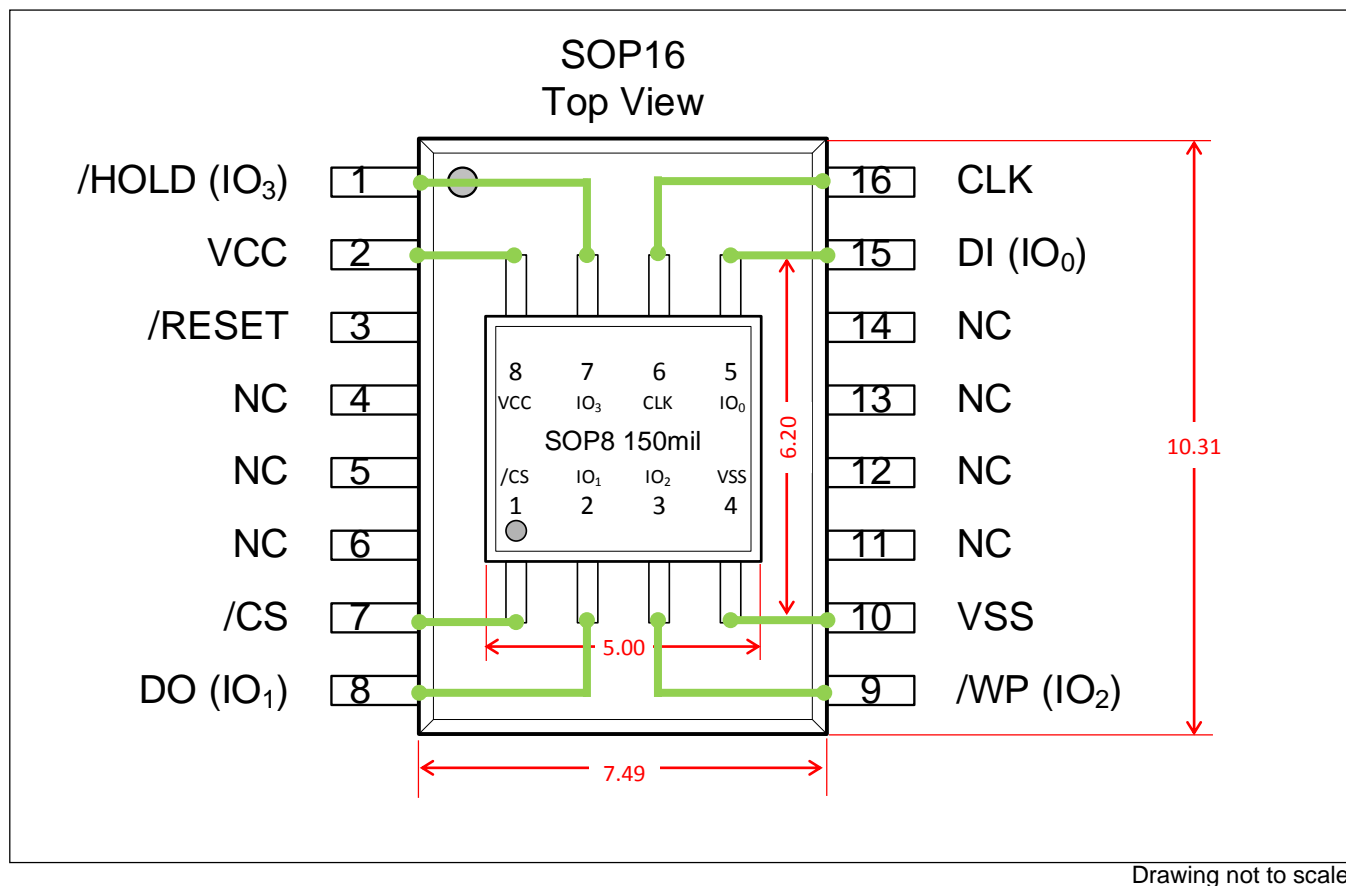


Introduction

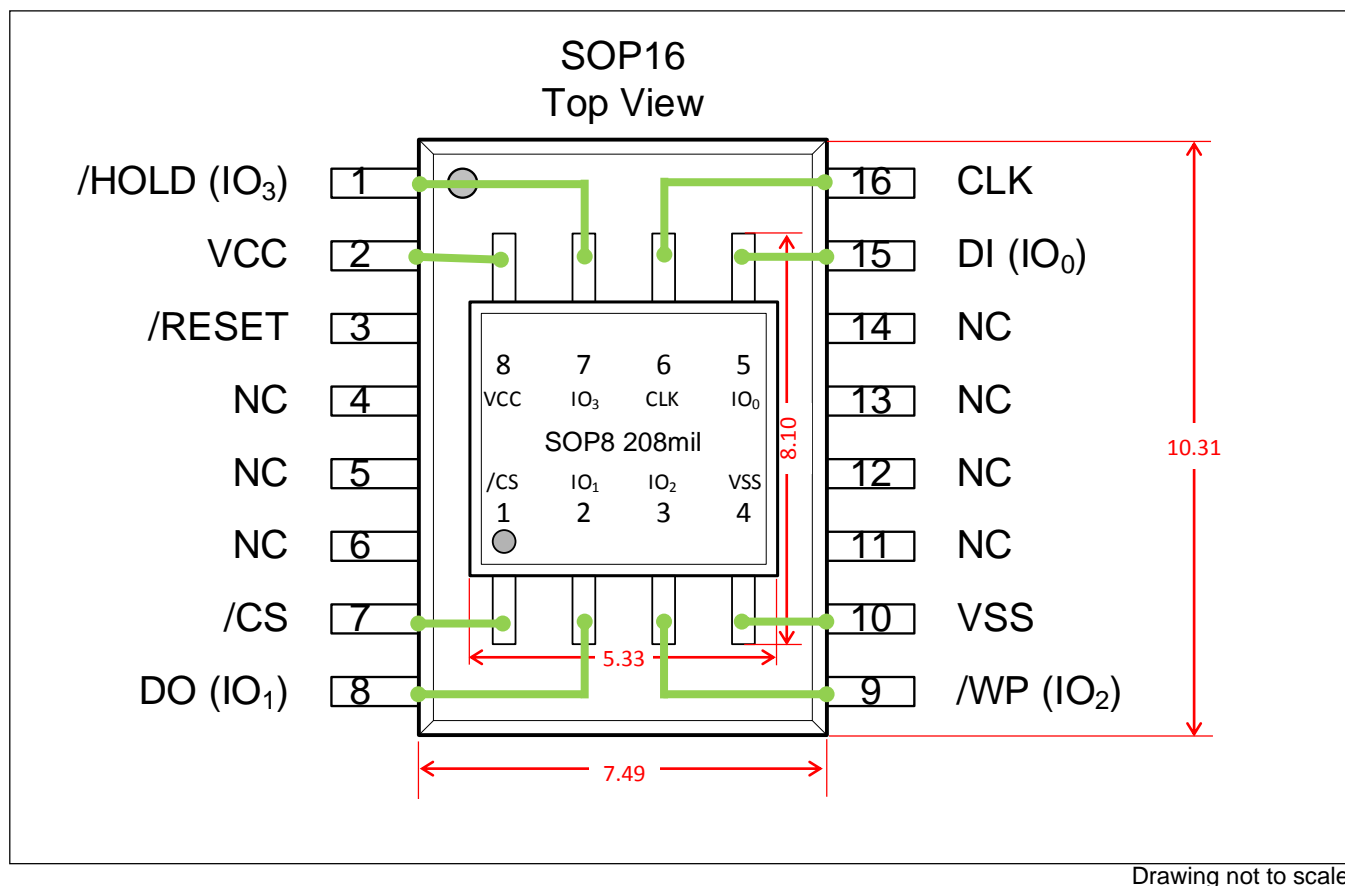
This application note explains how to create a dual layout that can accept a SOP16 300mil package (package code SF or F) with either a SOP8 150mil package (package code SN) or a SOP8 208mil package (package code SS or S).

Pinout Overlays

As illustrated in the following diagram, simply by rotating the SOP8 150mil package footprint by 90 degrees counterclockwise, the eight pins of the SOP8 package align with the SOP16 pin arrangement. As a result, a dual layout is possible between the SOP16 and the SOP8 150mil packages.



Similarly, a dual layout is also possible between the SOP16 and SOP8 208mil packages. Refer to the following illustration.



Note that IO[3:0] pins are multifunctional. Refer to the datasheets to confirm system level design compatibility.

Revision History

Version	Date	Page	Description
1.0	12/18/2023	NA	Original

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